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# Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

## **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	624
Number of Logic Elements/Cells	4992
Total RAM Bits	49152
Number of I/O	186
Number of Gates	257000
Voltage - Supply	2.375V ~ 2.625V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 70°C (TA)
Package / Case	256-BGA
Supplier Device Package	256-FBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep1k100fc256-3n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

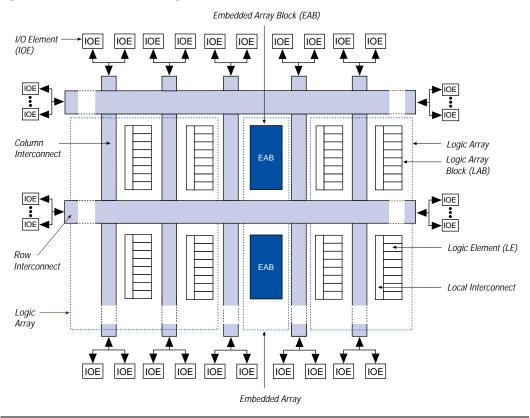
The logic array consists of logic array blocks (LABs). Each LAB contains eight LEs and a local interconnect. An LE consists of a 4-input LUT, a programmable flipflop, and dedicated signal paths for carry and cascade functions. The eight LEs can be used to create medium-sized blocks of logic—such as 8-bit counters, address decoders, or state machines—or combined across LABs to create larger logic blocks. Each LAB represents about 96 usable logic gates.

Signal interconnections within ACEX 1K devices (as well as to and from device pins) are provided by the FastTrack Interconnect routing structure, which is a series of fast, continuous row and column channels that run the entire length and width of the device.

Each I/O pin is fed by an I/O element (IOE) located at the end of each row and column of the FastTrack Interconnect routing structure. Each IOE contains a bidirectional I/O buffer and a flipflop that can be used as either an output or input register to feed input, output, or bidirectional signals. When used with a dedicated clock pin, these registers provide exceptional performance. As inputs, they provide setup times as low as 1.1 ns and hold times of 0 ns. As outputs, these registers provide clock-to-output times as low as 2.5 ns. IOEs provide a variety of features, such as JTAG BST support, slew-rate control, tri-state buffers, and open-drain outputs.

Figure 1 shows a block diagram of the ACEX 1K device architecture. Each group of LEs is combined into an LAB; groups of LABs are arranged into rows and columns. Each row also contains a single EAB. The LABs and EABs are interconnected by the FastTrack Interconnect routing structure. IOEs are located at the end of each row and column of the FastTrack Interconnect routing structure.

Figure 1. ACEX 1K Device Block Diagram



ACEX 1K devices provide six dedicated inputs that drive the flipflops' control inputs and ensure the efficient distribution of high-speed, low-skew (less than 1.0 ns) control signals. These signals use dedicated routing channels that provide shorter delays and lower skews than the FastTrack Interconnect routing structure. Four of the dedicated inputs drive four global signals. These four global signals can also be driven by internal logic, providing an ideal solution for a clock divider or an internally generated asynchronous clear signal that clears many registers in the device.

Each LAB provides four control signals with programmable inversion that can be used in all eight LEs. Two of these signals can be used as clocks, the other two can be used for clear/preset control. The LAB clocks can be driven by the dedicated clock input pins, global signals, I/O signals, or internal signals via the LAB local interconnect. The LAB preset and clear control signals can be driven by the global signals, I/O signals, or internal signals via the LAB local interconnect. The global control signals are typically used for global clock, clear, or preset signals because they provide asynchronous control with very low skew across the device. If logic is required on a control signal, it can be generated in one or more LEs in any LAB and driven into the local interconnect of the target LAB. In addition, the global control signals can be generated from LE outputs.

### Logic Element

The LE, the smallest unit of logic in the ACEX 1K architecture, has a compact size that provides efficient logic utilization. Each LE contains a 4-input LUT, which is a function generator that can quickly compute any function of four variables. In addition, each LE contains a programmable flipflop with a synchronous clock enable, a carry chain, and a cascade chain. Each LE drives both the local and the FastTrack Interconnect routing structure. Figure 8 shows the ACEX 1K LE.

#### **Clearable Counter Mode**

The clearable counter mode is similar to the up/down counter mode, but it supports a synchronous clear instead of the up/down control. The clear function is substituted for the cascade-in signal in the up/down counter mode. Two 3-input LUTs are used; one generates the counter data, and the other generates the fast carry bit. Synchronous loading is provided by a 2-to-1 multiplexer. The output of this multiplexer is AND ed with a synchronous clear signal.

#### Internal Tri-State Emulation

Internal tri-state emulation provides internal tri-states without the limitations of a physical tri-state bus. In a physical tri-state bus, the tri-state buffers' output enable (OE) signals select which signal drives the bus. However, if multiple OE signals are active, contending signals can be driven onto the bus. Conversely, if no OE signals are active, the bus will float. Internal tri-state emulation resolves contending tri-state buffers to a low value and floating buses to a high value, thereby eliminating these problems. The Altera software automatically implements tri-state bus functionality with a multiplexer.

#### Clear & Preset Logic Control

Logic for the programmable register's clear and preset functions is controlled by the DATA3, LABCTRL1, and LABCTRL2 inputs to the LE. The clear and preset control structure of the LE asynchronously loads signals into a register. Either LABCTRL1 or LABCTRL2 can control the asynchronous clear. Alternatively, the register can be set up so that LABCTRL1 implements an asynchronous load. The data to be loaded is driven to DATA3; when LABCTRL1 is asserted, DATA3 is loaded into the register.

During compilation, the compiler automatically selects the best control signal implementation. Because the clear and preset functions are active-low, the Compiler automatically assigns a logic high to an unused clear or preset.

The clear and preset logic is implemented in one of the following six modes chosen during design entry:

- Asynchronous clear
- Asynchronous preset
- Asynchronous clear and preset
- Asynchronous load with clear
- Asynchronous load with preset
- Asynchronous load without clear or preset

#### **Asynchronous Clear**

The flipflop can be cleared by either LABCTRL1 or LABCTRL2. In this mode, the preset signal is tied to VCC to deactivate it.

#### **Asynchronous Preset**

An asynchronous preset is implemented as an asynchronous load, or with an asynchronous clear. If DATA3 is tied to VCC, asserting LABCTRL1 asynchronously loads a one into the register. Alternatively, the Altera software can provide preset control by using the clear and inverting the register's input and output. Inversion control is available for the inputs to both LEs and IOEs. Therefore, if a register is preset by only one of the two LABCTRL signals, the DATA3 input is not needed and can be used for one of the LE operating modes.

#### **Asynchronous Preset & Clear**

When implementing asynchronous clear and preset, LABCTRL1 controls the preset, and LABCTRL2 controls the clear. DATA3 is tied to VCC, so that asserting LABCTRL1 asynchronously loads a one into the register, effectively presetting the register. Asserting LABCTRL2 clears the register.

#### **Asynchronous Load with Clear**

When implementing an asynchronous load in conjunction with the clear, LABCTRL1 implements the asynchronous load of DATA3 by controlling the register preset and clear. LABCTRL2 implements the clear by controlling the register clear; LABCTRL2 does not have to feed the preset circuits.

#### **Asynchronous Load with Preset**

When implementing an asynchronous load in conjunction with preset, the Altera software provides preset control by using the clear and inverting the input and output of the register. Asserting LABCTRL2 presets the register, while asserting LABCTRL1 loads the register. The Altera software inverts the signal that drives DATA3 to account for the inversion of the register's output.

#### Asynchronous Load without Preset or Clear

When implementing an asynchronous load without preset or clear, LABCTRL1 implements the asynchronous load of DATA3 by controlling the register preset and clear.

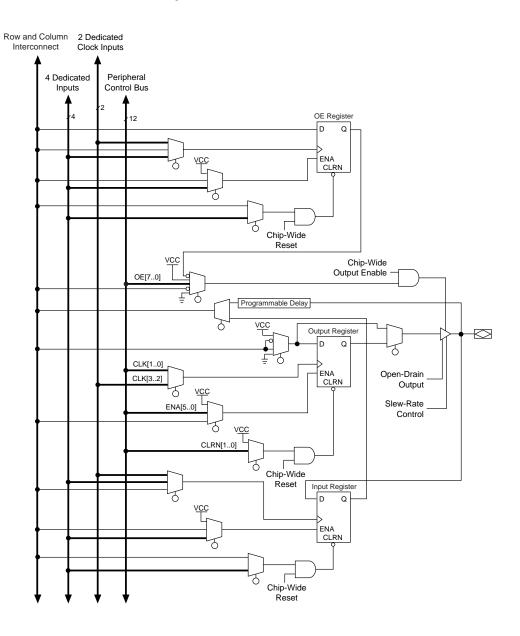
See Figure 17 for details. I/O Element (IOE) IOF IIOF IOE IOE IOE IOE Row LAB LAB See Figure 16 I AR Interconnect Α1 A2 АЗ for details. Column ►To LAB A5 Interconnect ►To LAB A4 IOE IOE LAB LAB I AR Cascade & B1 R2 В3 Carry Chains To LAB B5 ►To LAB B4 IOE IOE IOE

Figure 14. ACEX 1K Interconnect Resources

## I/O Element

An IOE contains a bidirectional I/O buffer and a register that can be used either as an input register for external data that requires a fast setup time or as an output register for data that requires fast clock-to-output performance. In some cases, using an LE register for an input register will result in a faster setup time than using an IOE register. IOEs can be used as input, output, or bidirectional pins. The compiler uses the programmable inversion option to invert signals from the row and column interconnect automatically where appropriate. For bidirectional registered I/O implementation, the output register should be in the IOE and the data input and output enable registers should be LE registers placed adjacent to the bidirectional pin. Figure 15 shows the bidirectional I/O registers.

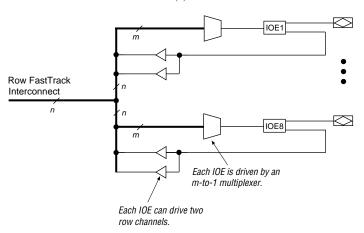
Figure 15. ACEX 1K Bidirectional I/O Registers



#### Row-to-IOE Connections

When an IOE is used as an input signal, it can drive two separate row channels. The signal is accessible by all LEs within that row. When an IOE is used as an output, the signal is driven by a multiplexer that selects a signal from the row channels. Up to eight IOEs connect to each side of each row channel (see Figure 16).

Figure 16. ACEX 1K Row-to-IOE Connections Note (1)



#### Note:

(1) The values for m and n are shown in Table 8.

Table 8 lists the ACEX 1K row-to-IOE interconnect resources.

Table 8. ACEX 1K Ro	B. ACEX 1K Row-to-IOE Interconnect Resources				
Device	Channels per Row (n)	Row Channels per Pin (m)			
EP1K10	144	18			
EP1K30	216	27			
EP1K50	216	27			
EP1K100	312	39			

# IEEE Std. 1149.1 (JTAG) Boundary-Scan Support

All ACEX 1K devices provide JTAG BST circuitry that complies with the IEEE Std. 1149.1-1990 specification. ACEX 1K devices can also be configured using the JTAG pins through the ByteBlasterMV or BitBlaster download cable, or via hardware that uses the Jam<sup>TM</sup> Standard Test and Programming Language (STAPL), JEDEC standard JESD-71. JTAG boundary-scan testing can be performed before or after configuration, but not during configuration. ACEX 1K devices support the JTAG instructions shown in Table 14.

Table 14. ACEX 1K J	TAG Instructions
JTAG Instruction	Description
SAMPLE/PRELOAD	Allows a snapshot of signals at the device pins to be captured and examined during normal device operation and permits an initial data pattern to be output at the device pins.
EXTEST	Allows the external circuitry and board-level interconnections to be tested by forcing a test pattern at the output pins and capturing test results at the input pins.
BYPASS	Places the 1-bit bypass register between the TDI and TDO pins, allowing the BST data to pass synchronously through a selected device to adjacent devices during normal operation.
USERCODE	Selects the user electronic signature (USERCODE) register and places it between the TDI and TDO pins, allowing the USERCODE to be serially shifted out of TDO.
IDCODE	Selects the IDCODE register and places it between TDI and TDO, allowing the IDCODE to be serially shifted out of TDO.
ICR Instructions	These instructions are used when configuring an ACEX 1K device via JTAG ports using a MasterBlaster, ByteBlasterMV, or BitBlaster download cable, or a Jam File (.jam) or Jam Byte-Code File (.jbc) via an embedded processor.

The instruction register length of ACEX 1K devices is 10 bits. The USERCODE register length in ACEX 1K devices is 32 bits; 7 bits are determined by the user, and 25 bits are pre-determined. Tables 15 and 16 show the boundary-scan register length and device IDCODE information for ACEX 1K devices.

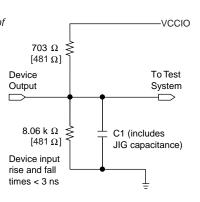
Table 15. ACEX 1K Boundary-Sc	an Register Length
Device	Boundary-Scan Register Length
EP1K10	438
EP1K30	690
EP1K50	798
EP1K100	1,050

# **Generic Testing**

Each ACEX 1K device is functionally tested. Complete testing of each configurable static random access memory (SRAM) bit and all logic functionality ensures 100% yield. AC test measurements for ACEX 1K devices are made under conditions equivalent to those shown in Figure 21. Multiple test patterns can be used to configure devices during all stages of the production flow.

Figure 21. ACEX 1K AC Test Conditions

Power supply transients can affect AC measurements. Simultaneous transitions of multiple outputs should be avoided for accurate measurement. Threshold tests must not be performed under AC conditions. Large-amplitude, fast-groundcurrent transients normally occur as the device outputs discharge the load capacitances. When these transients flow through the parasitic inductance between the device ground pin and the test system ground, significant reductions in observable noise immunity can result. Numbers in brackets are for 2.5-V devices or outputs. Numbers without brackets are for 3.3-V devices or outputs.



# Operating Conditions

Tables 18 through 21 provide information on absolute maximum ratings, recommended operating conditions, DC operating conditions, and capacitance for 2.5-V ACEX 1K devices.

Table 1	8. ACEX 1K Device Absolute I	Maximum Ratings Note (1)			
Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CCINT</sub>	Supply voltage	With respect to ground (2)	-0.5	3.6	V
V <sub>CCIO</sub>			-0.5	4.6	V
V <sub>I</sub>	DC input voltage		-2.0	5.75	V
I <sub>OUT</sub>	DC output current, per pin		-25	25	mA
T <sub>STG</sub>	Storage temperature	No bias	-65	150	° C
T <sub>AMB</sub>	Ambient temperature	Under bias	-65	135	° C
TJ	Junction temperature	PQFP, TQFP, and BGA packages, under bias		135	° C

Figure 22 shows the required relationship between  $V_{CCIO}$  and  $V_{CCINT}$  to satisfy 3.3-V PCI compliance.

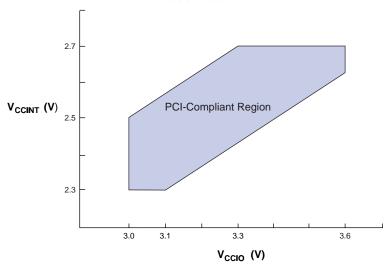
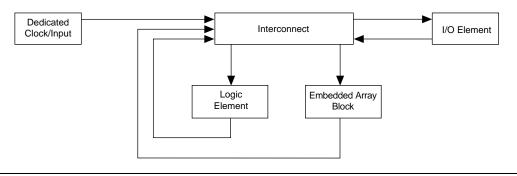


Figure 22. Relationship between  $V_{CCIO}$  &  $V_{CCINT}$  for 3.3-V PCI Compliance

Figure 23 shows the typical output drive characteristics of ACEX 1K devices with 3.3-V and 2.5-V  $V_{\rm CCIO}$ . The output driver is compliant to the 3.3-V *PCI Local Bus Specification, Revision 2.2* (when VCCIO pins are connected to 3.3 V). ACEX 1K devices with a -1 speed grade also comply with the drive strength requirements of the *PCI Local Bus Specification, Revision 2.2* (when VCCINT pins are powered with a minimum supply of 2.375 V, and VCCIO pins are connected to 3.3 V). Therefore, these devices can be used in open 5.0-V PCI systems.

Figure 24 shows the overall timing model, which maps the possible paths to and from the various elements of the ACEX 1K device.

Figure 24. ACEX 1K Device Timing Model



Figures 25 through 28 show the delays that correspond to various paths and functions within the LE, IOE, EAB, and bidirectional timing models.

Figure 25. ACEX 1K Device LE Timing Model

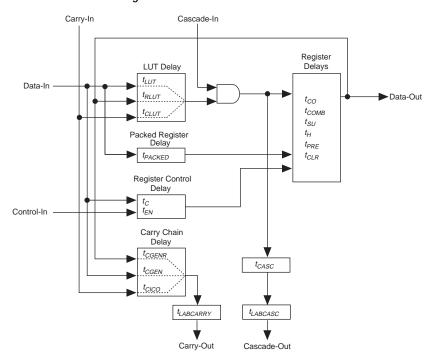


Figure 26. ACEX 1K Device IOE Timing Model

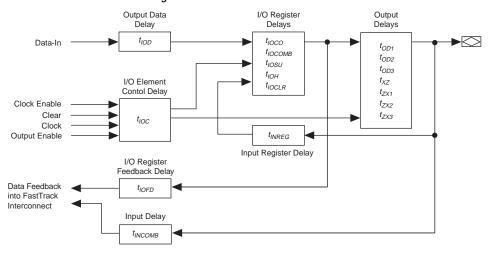


Figure 27. ACEX 1K Device EAB Timing Model

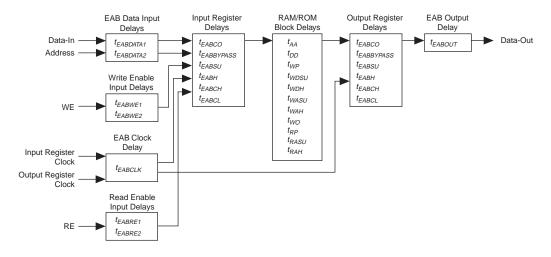
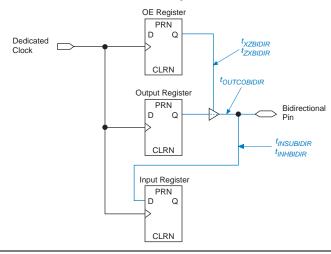


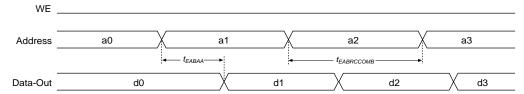
Figure 28. Synchronous Bidirectional Pin External Timing Model



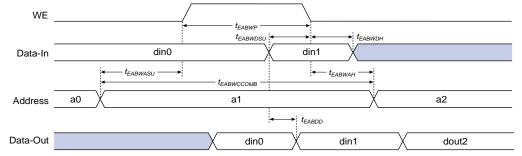
Tables 29 and 30 show the asynchronous and synchronous timing waveforms, respectively, for the EAB macroparameters in Table 24.

Figure 29. EAB Asynchronous Timing Waveforms





#### **EAB Asynchronous Write**



Tables 30 through 36 show EP1K10 device internal and external timing parameters.

Table 30. EP1K10	0 Device LE	Timing Micro	parameters	Note (1)			
Symbol		Unit					
	-	1	-	-2		-3	
	Min	Max	Min	Max	Min	Max	
$t_{LUT}$		0.7		0.8		1.1	ns
$t_{CLUT}$		0.5		0.6		0.8	ns
t <sub>RLUT</sub>		0.6		0.7		1.0	ns
t <sub>PACKED</sub>		0.4		0.4		0.5	ns
$t_{EN}$		0.9		1.0		1.3	ns
$t_{CICO}$		0.1		0.1		0.2	ns
t <sub>CGEN</sub>		0.4		0.5		0.7	ns
t <sub>CGENR</sub>		0.1		0.1		0.2	ns
$t_{CASC}$		0.7		0.9		1.1	ns
$t_{C}$		1.1		1.3		1.7	ns
$t_{\rm CO}$		0.5		0.7		0.9	ns
t <sub>COMB</sub>		0.4		0.5		0.7	ns
$t_{SU}$	0.7		0.8		1.0		ns
t <sub>H</sub>	0.9		1.0		1.1		ns
t <sub>PRE</sub>		0.8		1.0		1.4	ns
t <sub>CLR</sub>		0.9		1.0		1.4	ns
t <sub>CH</sub>	2.0		2.5		2.5		ns
$t_{CL}$	2.0		2.5		2.5		ns

Symbol			Speed	Grade			Unit
	-1		-2		-3		
	Min	Max	Min	Max	Min	Max	
t <sub>INSUBIDIR</sub> (2)	2.2		2.3		3.2		ns
t <sub>INHBIDIR</sub> (2)	0.0		0.0		0.0		ns
t <sub>OUTCOBIDIR</sub> (2)	2.0	6.6	2.0	7.8	2.0	9.6	ns
t <sub>XZBIDIR</sub> (2)		8.8		11.2		14.0	ns
t <sub>ZXBIDIR</sub> (2)		8.8		11.2		14.0	ns
t <sub>INSUBIDIR</sub> (4)	3.1		3.3		-	-	
t <sub>INHBIDIR</sub> (4)	0.0		0.0				•
toutcobidir (4)	0.5	5.1	0.5	6.4	-	_	ns
t <sub>XZBIDIR</sub> (4)		7.3		9.2		_	ns
t <sub>ZXBIDIR</sub> (4)		7.3		9.2		_	ns

#### Notes to tables:

- (1) All timing parameters are described in Tables 22 through 29 in this data sheet.
- (2) This parameter is measured without the use of the ClockLock or ClockBoost circuits.
- (3) These parameters are specified by characterization.
- (4) This parameter is measured with the use of the ClockLock or ClockBoost circuits.

Tables 37 through 43 show EP1K30 device internal and external timing parameters.

Symbol			Speed	Grade			Unit
	_	-1		-2		3	
	Min	Max	Min	Max	Min	Max	
$t_{LUT}$		0.7		0.8		1.1	ns
t <sub>CLUT</sub>		0.5		0.6		0.8	ns
t <sub>RLUT</sub>		0.6		0.7		1.0	ns
t <sub>PACKED</sub>		0.3		0.4		0.5	ns
$t_{EN}$		0.6		0.8		1.0	ns
t <sub>CICO</sub>		0.1		0.1		0.2	ns
t <sub>CGEN</sub>		0.4		0.5		0.7	ns
t <sub>CGENR</sub>		0.1		0.1		0.2	ns
t <sub>CASC</sub>		0.6		0.8		1.0	ns
t <sub>C</sub>		0.0		0.0		0.0	ns
t <sub>co</sub>		0.3		0.4		0.5	ns

Symbol			Speed	Grade			Unit
	-1		-2		-3		
	Min	Max	Min	Max	Min	Max	
t <sub>INSUBIDIR</sub> (2)	2.7		3.2		4.3		ns
t <sub>INHBIDIR</sub> (2)	0.0		0.0		0.0		ns
t <sub>INSUBIDIR</sub> (3)	3.7		4.2		-		ns
t <sub>INHBIDIR</sub> (3)	0.0		0.0		_		ns
t <sub>OUTCOBIDIR</sub> (2)	2.0	4.5	2.0	5.2	2.0	7.3	ns
t <sub>XZBIDIR</sub> (2)		6.8		7.8		10.1	ns
t <sub>ZXBIDIR</sub> (2)		6.8		7.8		10.1	ns
t <sub>OUTCOBIDIR</sub> (3)	0.5	3.5	0.5	4.2	=	-	
t <sub>XZBIDIR</sub> (3)		6.8		8.4		-	ns
t <sub>ZXBIDIR</sub> (3)		6.8		8.4	•	-	ns

#### Notes to tables:

- All timing parameters are described in Tables 22 through 29. This parameter is measured without use of the ClockLock or ClockBoost circuits. (2)
- This parameter is measured with use of the ClockLock or ClockBoost circuits (3)

Symbol		Speed Grade							
	-1		-2		-	3			
	Min	Max	Min	Max	Min	Max			
$t_{IOD}$		1.7		2.0		2.6	ns		
t <sub>IOC</sub>		0.0		0.0		0.0	ns		
t <sub>IOCO</sub>		1.4		1.6		2.1	ns		
t <sub>IOCOMB</sub>		0.5		0.7		0.9	ns		
t <sub>IOSU</sub>	0.8		1.0		1.3		ns		
t <sub>IOH</sub>	0.7		0.9		1.2		ns		
t <sub>IOCLR</sub>		0.5		0.7		0.9	ns		
t <sub>OD1</sub>		3.0		4.2		5.6	ns		
t <sub>OD2</sub>		3.0		4.2		5.6	ns		
t <sub>OD3</sub>		4.0		5.5		7.3	ns		
$t_{XZ}$		3.5		4.6		6.1	ns		
$t_{ZX1}$		3.5		4.6		6.1	ns		
$t_{ZX2}$		3.5		4.6		6.1	ns		
$t_{ZX3}$		4.5		5.9		7.8	ns		
t <sub>INREG</sub>		2.0		2.6		3.5	ns		
t <sub>IOFD</sub>		0.5		0.8		1.2	ns		
t <sub>INCOMB</sub>		0.5		0.8		1.2	ns		

Symbol	Speed Grade							
	-1		-2		-3			
	Min	Max	Min	Max	Min	Max		
t <sub>EABDATA1</sub>		1.5		2.0		2.6	ns	
t <sub>EABDATA1</sub>		0.0		0.0		0.0	ns	
t <sub>EABWE1</sub>		1.5		2.0		2.6	ns	
t <sub>EABWE2</sub>		0.3		0.4		0.5	ns	
t <sub>EABRE1</sub>		0.3		0.4		0.5	ns	
t <sub>EABRE2</sub>		0.0		0.0		0.0	ns	
t <sub>EABCLK</sub>		0.0		0.0		0.0	ns	
t <sub>EABCO</sub>		0.3		0.4		0.5	ns	
t <sub>EABBYPASS</sub>		0.1		0.1		0.2	ns	
t <sub>EABSU</sub>	0.8		1.0		1.4		ns	
t <sub>EABH</sub>	0.1		0.1		0.2		ns	
t <sub>EABCLR</sub>	0.3		0.4		0.5		ns	
$t_{AA}$		4.0		5.1		6.6	ns	
$t_{WP}$	2.7		3.5		4.7		ns	
$t_{RP}$	1.0		1.3		1.7		ns	
t <sub>WDSU</sub>	1.0		1.3		1.7		ns	
$t_{WDH}$	0.2		0.2		0.3		ns	
t <sub>WASU</sub>	1.6		2.1		2.8		ns	
t <sub>WAH</sub>	1.6		2.1		2.8		ns	
t <sub>RASU</sub>	3.0		3.9		5.2		ns	
t <sub>RAH</sub>	0.1		0.1		0.2		ns	
$t_{WO}$		1.5		2.0		2.6	ns	
t <sub>DD</sub>		1.5		2.0		2.6	ns	
t <sub>EABOUT</sub>		0.2		0.3		0.3	ns	
t <sub>EABCH</sub>	1.5		2.0		2.5		ns	
t <sub>EABCL</sub>	2.7		3.5		4.7		ns	



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